

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title:	Expanding supply to ADI's Beaverton/Oregon foundry (ADBN) for MAX17823BGCB/V+ automotive device (BP05F-2B)
Publication Date:	25-May-2022
Effectivity Date:	27-Aug-2022 (the earliest date that a customer could expect to receive changed material)
Revision Description:	

Description Of Change:

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MAX17823BGCB/V+ automotive device
Current waferfab at Epson/Sakata/Japan
Current waferfab at Tower Semiconductor/San Antonio/Texas

Reason For Change:

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ADI is experiencing severe capacity constraints at current fab Epson. Adding ADBN fab is to ensure supply continuity and to meet customers increasing demands.
ADBN qualification report is attached.
There will be no changes to Form/Fit/Function of the device.

Impact of the change (positive or negative) on fit, form, function & reliability:

Product Identification (this section will describe how to identify the changed material):

Summary of Supporting Information:

Supporting Documents:

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Korea:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

Appendix A - Impacted items, see csv PN listing in PCN Zip file